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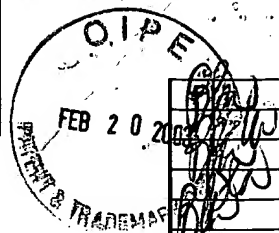
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| | | | | First Named Inventor | Gene R. Anderson |
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| | | | | Examiner Name | Webb, Brian Scott |
| (use as many sheets as necessary) | | | | Attorney Docket Number | 1613370-0013 |
| Sheet | 1 | of | 2 | | |

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